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Materials Declaration

Company Name : Fox Electronics

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Completed by Bruce Clark

Date : September 25, 2005

Product Family : 5x12.9x5mm Plastic Package Crvstal (FPXLF)

*Revised 12/18/07

** Added 3/25/2011

	Material Name	Component	Content (mg)	Content (w t %)	(CAS Number)
Cover	Nickel Silver	Nickel (Ni)	17.02	3.197%	7440-02-0
		Copper (Cu)	53.65	10.078%	7440-50-8
		Zinc (Zn)	32.50	6.105%	7440-66-6
	Nickel Plating	Nickel (Ni)	3.83	0.719%	7440-02-0
Base	Alloy 42	Iron (Fe)	8.80	1.653%	7439-89-6
		Nickel (Ni)	6.30	1.183%	7440-02-0
	Glass	Silicon Dioxide (SiO ₂)	8.13	1.527%	14808-60-7
	Kovar	Iron (Fe)	8.62	1.619%	7439-89-6
		Nickel (Ni)	4.63	0.870%	7440-02-0
		Cobalt (Co)	2.71	0.509%	7440-48-4
	Copper Plating	Copper (Cu)	1.00	0.188%	7440-50-8
	Silver Plating	Silver (Ag)	0.59	0.111%	7440-22-4
	Solder Plating	Tin (Sn)	0.30	0.0564%	7440-31-5
		Lead (Pb)**	3.92	0.736%	7439-92-1
Plastic Mold	Epoxy Molding Compound	Silica-Fused (SiO ₂)	270.0000	50.71918%	60676-86-0
		Epoxy Resin	27.0000	5.07192%	
		Phenolic Resin	27.0000	5.07192%	
		Mixed Siloxanes	10.1250	1.90197%	
		Antimony Oxide (Sb ₂ O ₃)	1.1250	0.21133%	1309-64-4
		Brominated Compound	1.1250	0.21133%	
		Carbon Black	1.1250	0.21133%	1333-86-4
Leadframe	Brass	Copper (Cu)	20.4000	3.832%	7440-50-8
		Zinc (Zn)	9.600	1.80%	7440-66-6
	Nickel Plating	Nickel (Ni)	1.880	0.35%	7440-02-0
	Termination Plating	*Matte Tin (Sn)	5.630	1.058%	7440-31-5
Crystal	Crystal	Silicon Dioxide (SiO ₂)	5.22	0.98%	14808-60-7
		Electrode	Silver (Ag)	0.040	0.0075%
		Nickel (Ni)	0.001	0.0002%	7440-02-0
	Adhesive	Silver (Ag)	0.03000	0.005635%	7440-22-4
		Epoxy	0.042000	0.007890%	
TOTAL			532.34	100.00%	

** Covered by Exemption 7(a) - Lead in high melting temperature solders(i.e., lead-based alloys containing 85% by weight or more lead)